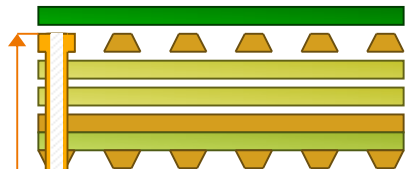
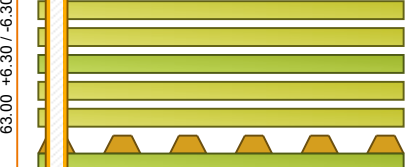
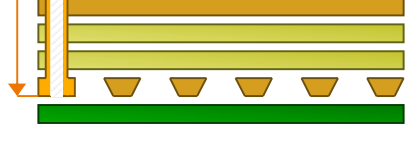
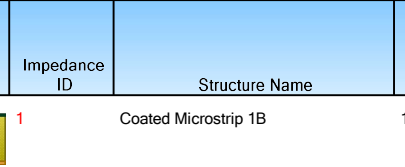
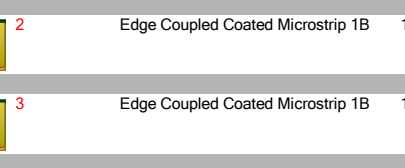
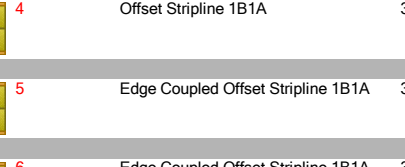















Layer	Stack up	Type	Supplier	Supplier Description	Description	Base Thickness	Impedance ID	Mask Thickness	Processed Thickness	εr
1		SolderMask		SM INK	Liquid PhotolImageable Mask			1.969	1.969	4.100
		copper			Copper Foil	0.315	1, 2, 3		1.496	
		FR4	isola	HIGH TG	PrePreg 106	1.969			1.939	3.760
2		FR4	isola	HIGH TG	PrePreg 106	1.969			1.939	3.760
		FR4	isola	HIGH TG	Core	1.181			1.181	
		FR4	isola	HIGH TG	Core	4.921			4.921	4.040
3		FR4	isola	HIGH TG	Core	1.181	4, 5, 6		1.181	
		FR4	isola	HIGH TG	PrePreg 106	1.969			1.583	3.760
		FR4	isola	HIGH TG	PrePreg 1080	2.559			2.058	3.930
4		FR4	isola	HIGH TG	Core	27.953			27.953	4.360
		FR4	isola	HIGH TG	PrePreg 1080	2.559			2.058	3.930
		FR4	isola	HIGH TG	PrePreg 106	1.969			1.583	3.760
5		FR4	isola	HIGH TG	Core	1.181	7, 8, 9		1.181	
		FR4	isola	HIGH TG	Core	4.921			4.921	4.040
		FR4	isola	HIGH TG	PrePreg 106	1.181			1.181	
6		FR4	isola	HIGH TG	PrePreg 106	1.969			1.939	3.760
		FR4	isola	HIGH TG	PrePreg 106	1.969			1.939	3.760
		copper			Copper Foil	0.315	10, 11, 12		1.496	
		SolderMask		SM INK	Liquid PhotolImageable Mask			1.969	1.969	4.100

Copper Thickness = 7.717 | Dielectric Thickness = 52.835 | Solder Mask Thickness = 3.937 | Stack Up Thickness = 60.551 | Stack Up Thickness with Soldermask = 64.488


Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)
	1	Coated Microstrip 1B	1	2	0	5.600	0.000	0.000	52.180	50.000	10.000
	2	Edge Coupled Coated Microstrip 1B	1	2	0	5.000	5.500	0.000	90.390	90.000	10.000
	3	Edge Coupled Coated Microstrip 1B	1	2	0	4.000	6.000	0.000	99.860	100.000	10.000
	4	Offset Stripline 1B1A	3	2	5	5.600	0.000	0.000	52.780	50.000	10.000
	5	Edge Coupled Offset Stripline 1B1A	3	2	5	5.000	5.500	0.000	87.430	90.000	10.000
	6	Edge Coupled Offset Stripline 1B1A	3	2	5	4.000	6.000	0.000	96.370	100.000	10.000

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor
Date: 05-02-2020	Associated Documents:				
Author: Pawan Kumar					
Department: Pre-Engineering					
Site: http://www.micro-pack.com/					

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	
	7	Offset Stripline 1B1A	4	2	5	5.600	0.000	0.000	52.780	50.000	10.000	
	8	Edge Coupled Offset Stripline 1B1A	4	2	5	5.000	5.500	0.000	87.430	90.000	10.000	
	9	Edge Coupled Offset Stripline 1B1A	4	2	5	4.000	6.000	0.000	96.370	100.000	10.000	
	10	Coated Microstrip 1B	6	5	0	5.600	0.000	0.000	52.180	50.000	10.000	
	11	Edge Coupled Coated Microstrip 1B	6	5	0	5.000	5.500	0.000	90.390	90.000	10.000	
	12	Edge Coupled Coated Microstrip 1B	6	5	0	4.000	6.000	0.000	99.860	100.000	10.000	

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type	
	1	6	1	Mechanical PTH	

Notes

StackName:	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 2/2	
Date: 05-02-2020	Associated Documents:						
Author: Pawan Kumar							
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